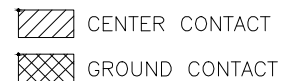
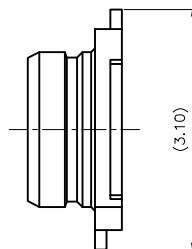
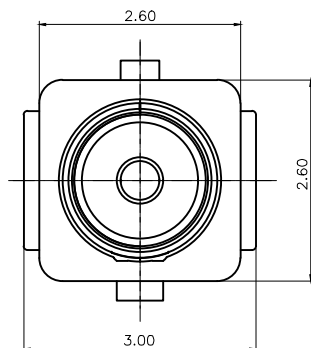
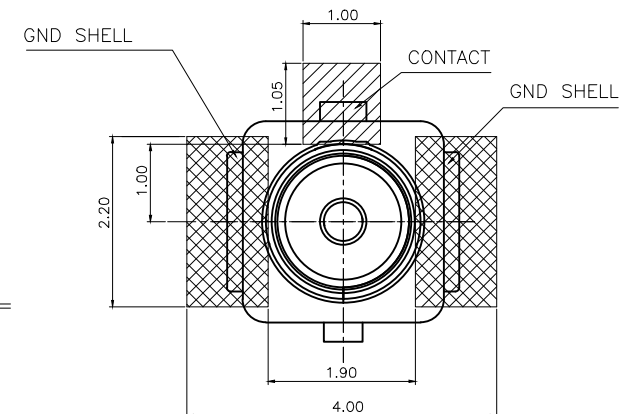


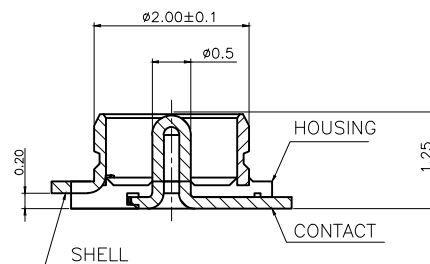
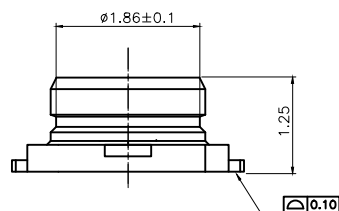
REV.	变更原因/内容	时间	变更人
A 0	最新版		



RECOMMENDED PCB LAYOUT
(TOLERANCE:±0.05)

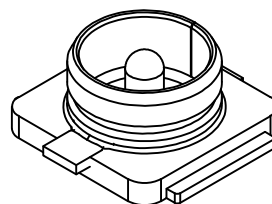
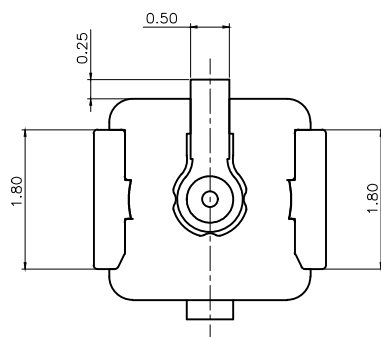


RECOMMENDED PCB LAYOUT
(TOLERANCE:±0.05)



NOTE:

- HOUSING MATERIAL: THERMOPLASTIC, BLACK, UL 94V-0;
CONTACT MATERIAL: COPPER ALLOY;
GOLD PLATED: CONTACT AREA 1u" Min & SOLDER AREA 1u" Min;
SHELL MATERIAL: COPPER ALLOY;
GOLD PLATED: CONTACT AREA 0.0508um Min & SOLDER AREA 0.0254um Min;
- PERFORMANCE:
 - CONTACT RESISTANCE: 20mOHM Max.
 - DIELECTRIC WITHSTANDING VOLTAGE: 100V AC FOR 1MINUTE;
 - INSULATION RESISTANCE: 500MOHM Min.
- COPLANARITY: 0.1mm Max.
- APPLIED TO IR SOLDERING PROCESS.



						型号: DL-IPEX-I	设计:
						名称: 一代板端3脚	审核:
标记	处数	分区	更改文件号	签名	日期	料号:	核准:
一般公差			比例:			 深圳市骏晔科技有限公司	
X.	±0.3		单位:	mm			
.X	±0.2		视图:				
.XX	±0.1		页码:	1/1			